

APPLICABLE STANDARD					
	Operating Temperature Range	-55 °C to +105 °C ⁽¹⁾	Storage Temperature Range	-10 °C to +60 °C ⁽²⁾	
Rating	Voltage	100 V AC	Storage Humidity Range	Relative humidity 85 % MAX (Not dewed)	
	Current	0.5 A	Operating Humidity Range		
SPECIFICATIONS					
ITEM	TEST METHOD		REQUIREMENTS	QT	AT
CONSTRUCTION					
General Examination	Visually and by measuring instrument.		According to drawing.	×	×
Marking	Confirmed visually.			×	×
ELECTRIC CHARACTERISTICS					
Contact Resistance	100 mA(DC or 1000 Hz)		30 mΩ MAX ⁽³⁾	×	—
Insulation Resistance	250 V DC		1000 MΩ MIN	×	—
Voltage Proof	300 V AC for 1 min.		No flashover or breakdown.	△ ₁	×
MECHANICAL CHARACTERISTICS					
Insertion and Withdrawal Forces	Measured by applicable connector.		Insertion Force: 26.7 N MAX Withdrawal Force: 2.7 N MIN	×	—
Mechanical Operation	100 times insertions and extractions.		1)Contact Resistance : 40 mΩ MAX ⁽³⁾ 2)No damage, crack and looseness of parts.	×	—
Vibration	Frequency 10 to 55 to 10 Hz, approx 5 min. Single amplitude: 0.75 mm, 10 cycles for 3 axial directions.		1)No electrical discontinuity of 1 μs. 2)No damage, crack and looseness of parts.	×	—
Shock	490 m/s ² , duration of pulse 11 ms at 3 times for 3 both axial directions.			×	—
ENVIRONMENTAL CHARACTERISTICS					
Damp Heat (Steady state)	Exposed at 40 ± 2 °C, 90 to 95 %, 96 h.		1)Contact Resistance : 40 mΩ MAX ⁽³⁾ 2) Insulation Resistance: 1000 MΩ MIN 3)No damage, crack and looseness of parts.	×	—
Rapid Change of Temperature	Temperature: -55 → +85 °C Time : 30 → 30 min. Under 5 cycles. (Relocation time to chamber: within 2 to 3 MIN)			×	—
Dry Heat	Exposed at +105 °C, 96 h		1)Contact Resistance : 40 mΩ MAX ⁽³⁾ 2)No damage, crack and looseness of parts.	×	—
Cold	Exposed at -55 °C, 96 h			×	—
Resistance to Soldering Heat	1)Reflow soldering: Peak TMP: 260 °C MAX Reflow TMP: 220 °C MIN for 60 sec 2)Soldering irons: 360 °C MAX for 5 sec.		No deformation of case of excessive looseness of the terminal.	×	—
Solderability	Soldered at solder temperature 240 ± 3 °C for immersion duration, 3 sec.		A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed.	×	—
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
△ ₁	2	DIS-F-00003292	MT. ITANO	HT. YAMAGUCHI	18. 04. 16
REMARKS			APPROVED	NH. NAKATA	17. 11. 01
(1) Include temperature rise caused by current-carrying.			CHECKED	MK. NAGATA	17. 10. 31
(2) "Storage" means a long-term storage state for the unpacked part before assembly to pcb.			DESIGNED	KJ. NISHIWAKI	17. 10. 31
(3) Contact resistance of relay board is not included. It becomes contact resistance for 1 connector. △ ₁			DRAWN	KJ. NISHIWAKI	17. 10. 31
Unless otherwise specified, refer to IEC 60512.					
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.	ELC-376551-00-00	
HRS	SPECIFICATION SHEET		PART NO.	FX27-40S-0.8SV	
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL577-1002-0-00	△ ₁ 1/1